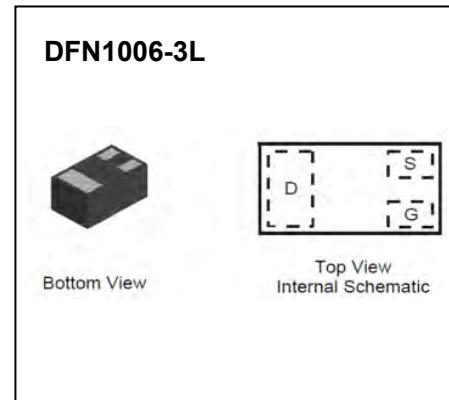


DFN1006-3L Plastic-Encapsulate MOSFETs

CJBA3541K N-Channel MOSFET

V_{(BR)DSS}	R_{DS(on)MAX}	I_D
30V	500mΩ@4.5V	0.6A
	600mΩ@2.5V	



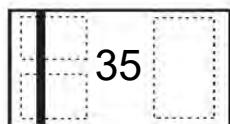
FEATURE

- Lead Free Product is Acquired
- Surface Mount Package
- N-Channel Switch with Low R_{DS(on)}
- Operated at Low Logic Level Gate Drive
- ESD Protected Gate

APPLICATION

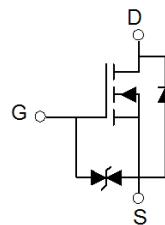
- Load/ Power Switching
- Interfacing Switching
- Battery Management for Ultra Small Portable Electronics
- Logic Level Shift

MARKING:



Top View
Bar Denotes Gate
and Source Side

Equivalent Circuit



ABSOLUTE MAXIMUM RATINGS (T_a=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V _{DS}	30	V
Typical Gate-Source Voltage	V _{GS}	±12	V
Continuous Drain Current (note 1)	I _D	0.6	A
Pulsed Drain Current (tp=10us)	I _{DM}	1.8	A
Power Dissipation (note 1)	P _D	100	mW
Thermal Resistance from Junction to Ambient (note 1)	R _{θJA}	1250	°C/W
Junction Temperature	T _J	150	°C
Storage Temperature	T _{STG}	-55~ 150	°C
Lead Temperature for Soldering Purposes(1/8" from case for 10 s)	T _L	260	°C

MOSFET ELECTRICAL CHARACTERISTICS

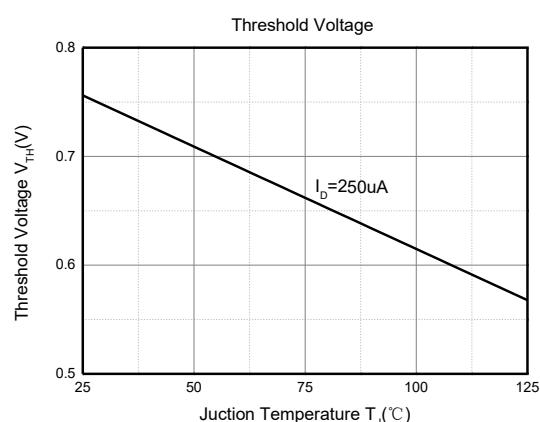
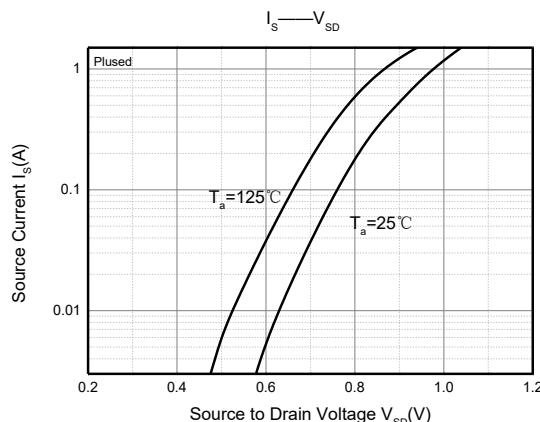
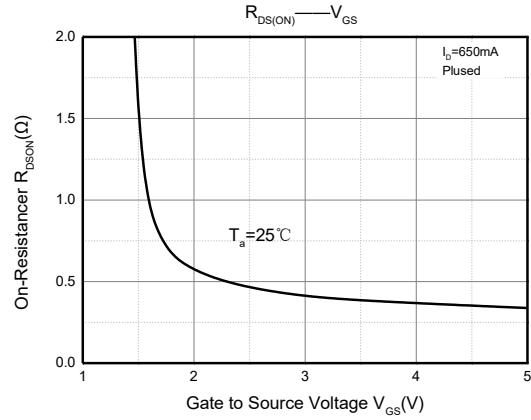
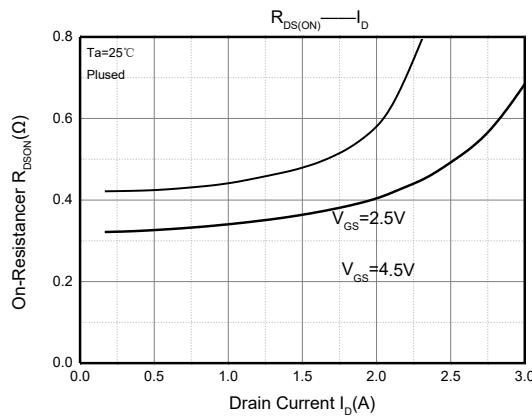
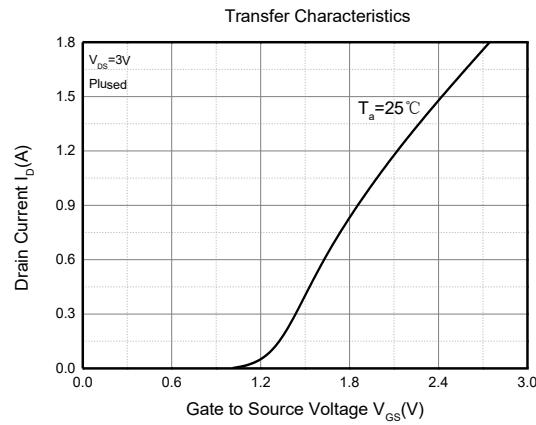
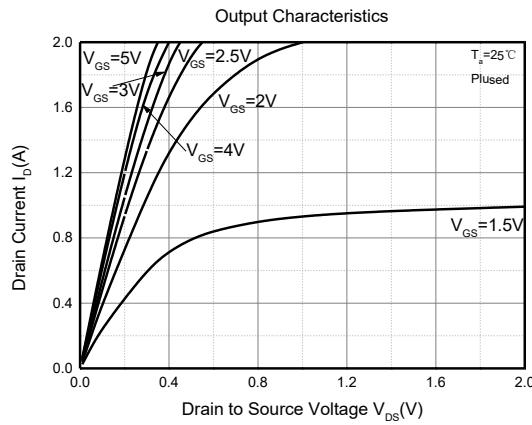
T_a=25°C unless otherwise noted

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	30			V
Zero gate voltage drain current	I _{DSS}	V _{DS} = 30V, V _{GS} = 0V			1	μA
Gate-body leakage current	I _{GSS}	V _{GS} = ±10V, V _{DS} = 0V			±20	μA
Gate threshold voltage ⁽²⁾	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	0.8	1.0	1.5	V
Drain-source on-resistance ⁽²⁾	R _{DS(on)}	V _{GS} = 4.5V, I _D = 600mA		320	500	mΩ
		V _{GS} = 2.5V, I _D = 300mA		410	600	
Forward transconductance	g _{FS}	V _{DS} = 10V, I _D = 150mA	150			mS
Dynamic characteristics⁽⁴⁾						
Input Capacitance	C _{iss}	V _{DS} = 16V, V _{GS} = 0V, f = 1MHz		44	120	pF
Output Capacitance	C _{oss}			15	20	
Reverse Transfer Capacitance	C _{rss}			8	15	
Switching Characteristics⁽⁴⁾						
Turn-on delay time ⁽³⁾	t _{d(on)}	V _{DS} = 10V, I _D = 500mA, V _{GS} = 4.5V, R _G = 10Ω		5.0		ns
Turn-on rise time ⁽³⁾	t _r			8.2		
Turn-off delay time ⁽³⁾	t _{d(off)}			23		
Turn-off fall time ⁽³⁾	t _f			41		
Source-Drain Diode characteristics						
Diode Forward voltage ⁽³⁾	V _{DS}	I _S = 0.15A, V _{GS} = 0V			1.2	V

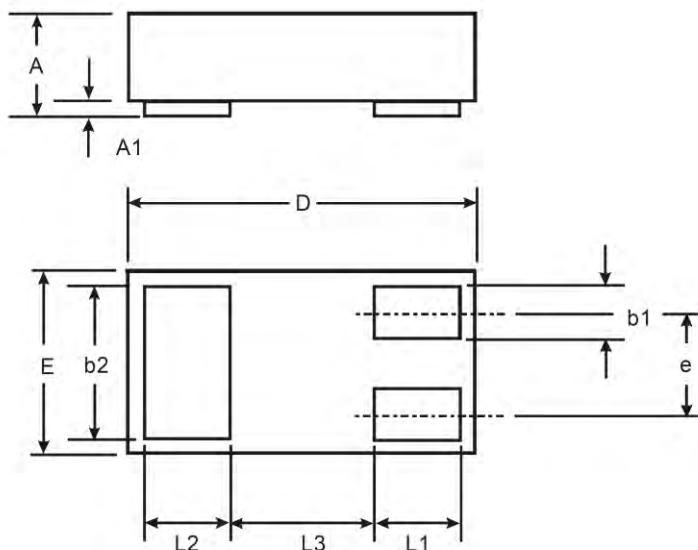
Notes:

1. Surface mounted on FR4 board using the minimum recommended pad size.
2. Pulse Test : Pulse Width=300μs, Duty Cycle=2%.
3. Switching characteristics are independent of operating junction temperatures.
4. Guaranteed by design, not subject to producting.

Typical Characteristics



DFN1006-3L Package Outline Dimensions



X1-DFN1006-3			
Dim	Min	Max	Typ
A	0.47	0.53	0.50
A1	0	0.05	0.03
b1	0.10	0.20	0.15
b2	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	—	—	0.35
L1	0.20	0.30	0.25
L2	0.20	0.30	0.25
L3	—	—	0.40

All Dimensions in mm

NOTICE

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